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Bond et al.

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(54) **MOLDED FINGERPRINT SENSOR
STRUCTURE WITH INDICIA REGIONS**

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(**) Term: **14 Years**

(21) Appl. No.: **29/357,084**

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(51) **LOC (9) Cl.** **10-05**

(52) **U.S. Cl.** **D10/104.1**

(58) **Field of Classification Search** D10/104.1,
D10/106.6; D14/140.5, 384; 235/382; 382/124
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D328,594	S *	8/1992	Kobayashi	D14/424
D346,340	S *	4/1994	Cayton et al.	D10/106.1
D351,144	S *	10/1994	Fishbine et al.	D14/384
D362,252	S *	9/1995	Ansell et al.	D14/144
D367,270	S *	2/1996	Levering	D14/384
5,844,287	A	12/1998	Hassan et al.		
5,864,296	A	1/1999	Upton		
5,942,761	A	8/1999	Tuli		
6,061,464	A1	8/2001	Belongie et al.		
6,272,562	B1 *	8/2001	Scott et al.	710/16
6,687,391	B1 *	2/2004	Scott et al.	382/126
6,980,286	B1	12/2005	Feng		
D516,069	S *	2/2006	Kuroda et al.	D14/384
7,147,153	B2	12/2006	Rowe et al.		

OTHER PUBLICATIONS

Rowe, Robert K., "A Multispectral Sensor for Fingerprint Spoof Detection", *Sensors*, vol. 22, No. 1, (Jan. 2005), pp. 2-4.
<http://www.validityinc.com/post.aspx?id=147>, "Validity Launches the First Customizable LED Fingerprint Sensor", Jan. 8, 2009.
www.boschman.nl/technology/technology.htm.

* cited by examiner

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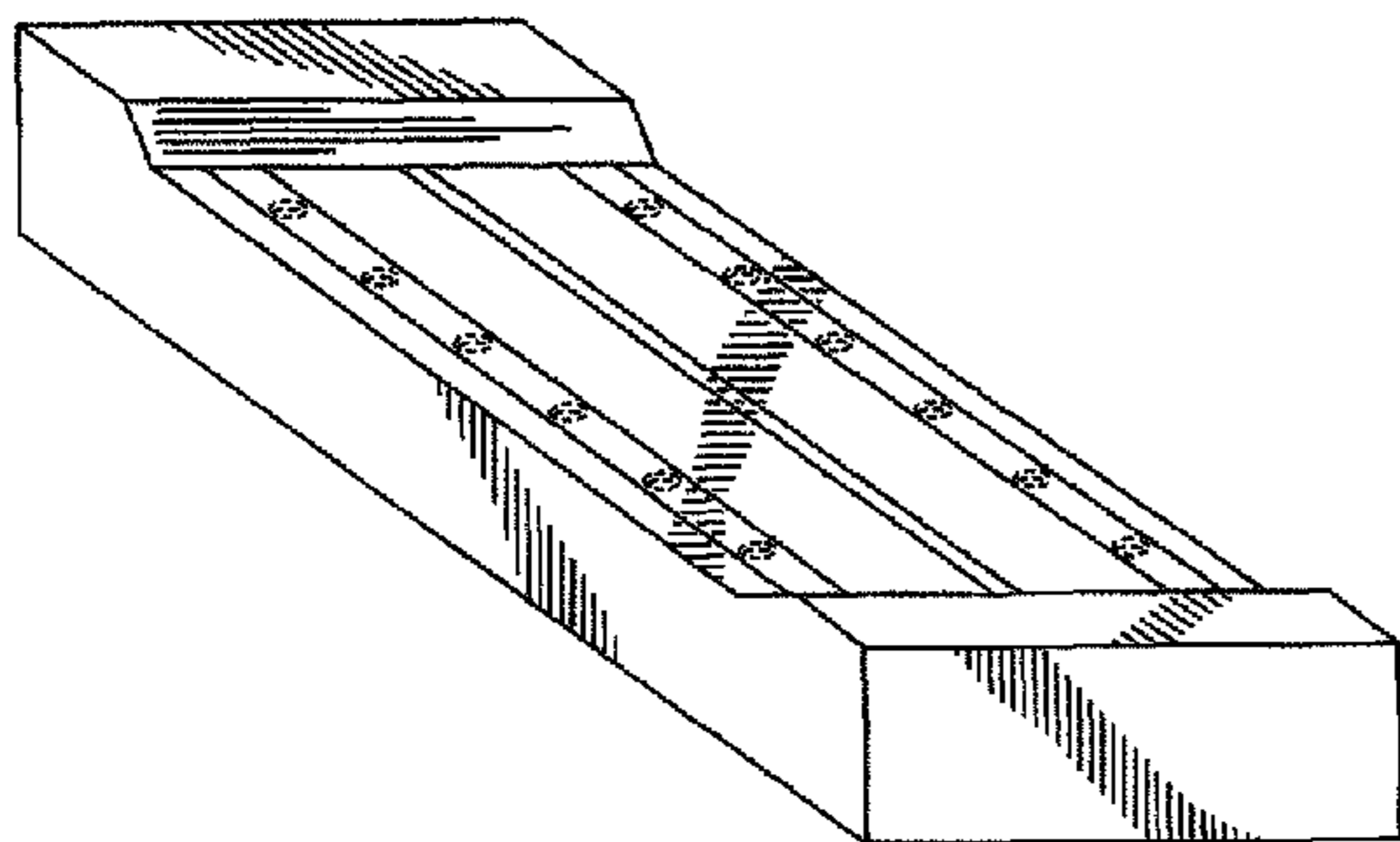
(57) **CLAIM**

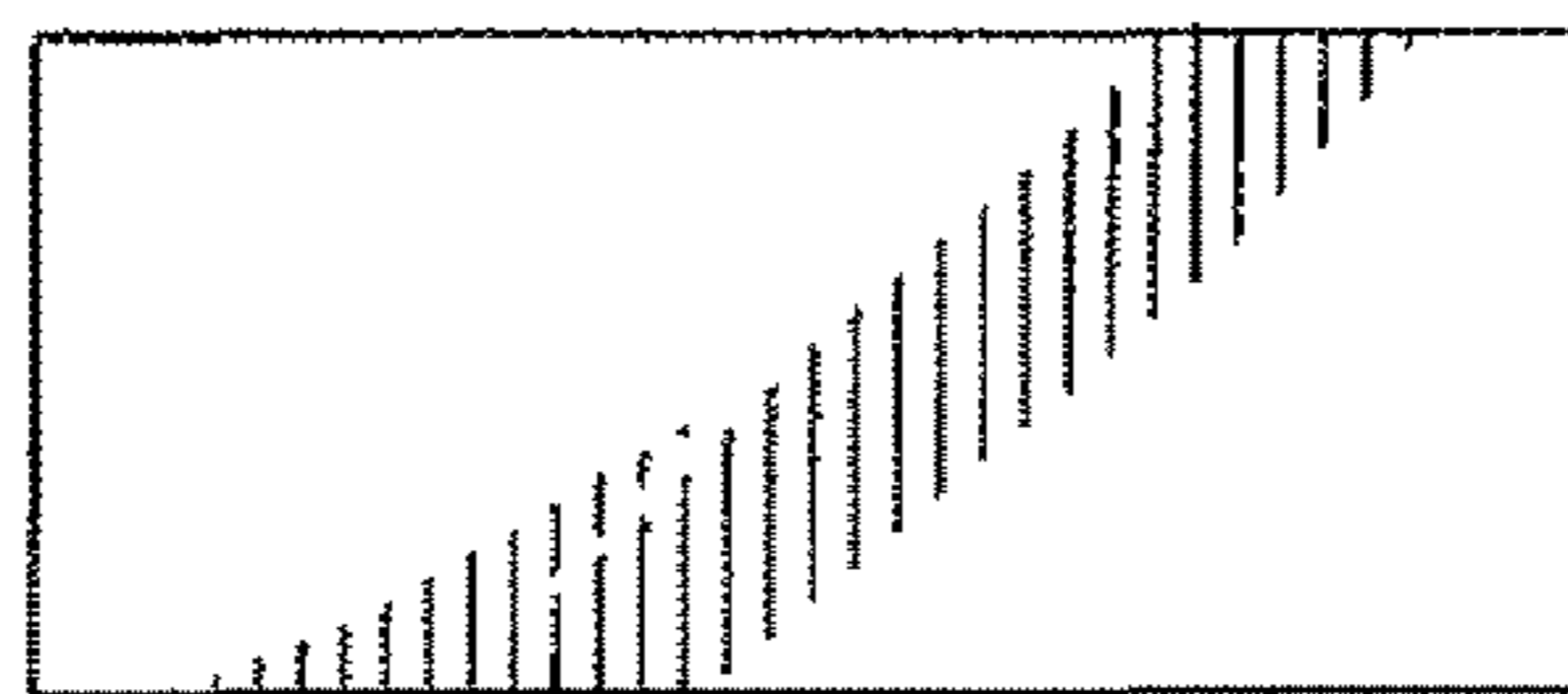
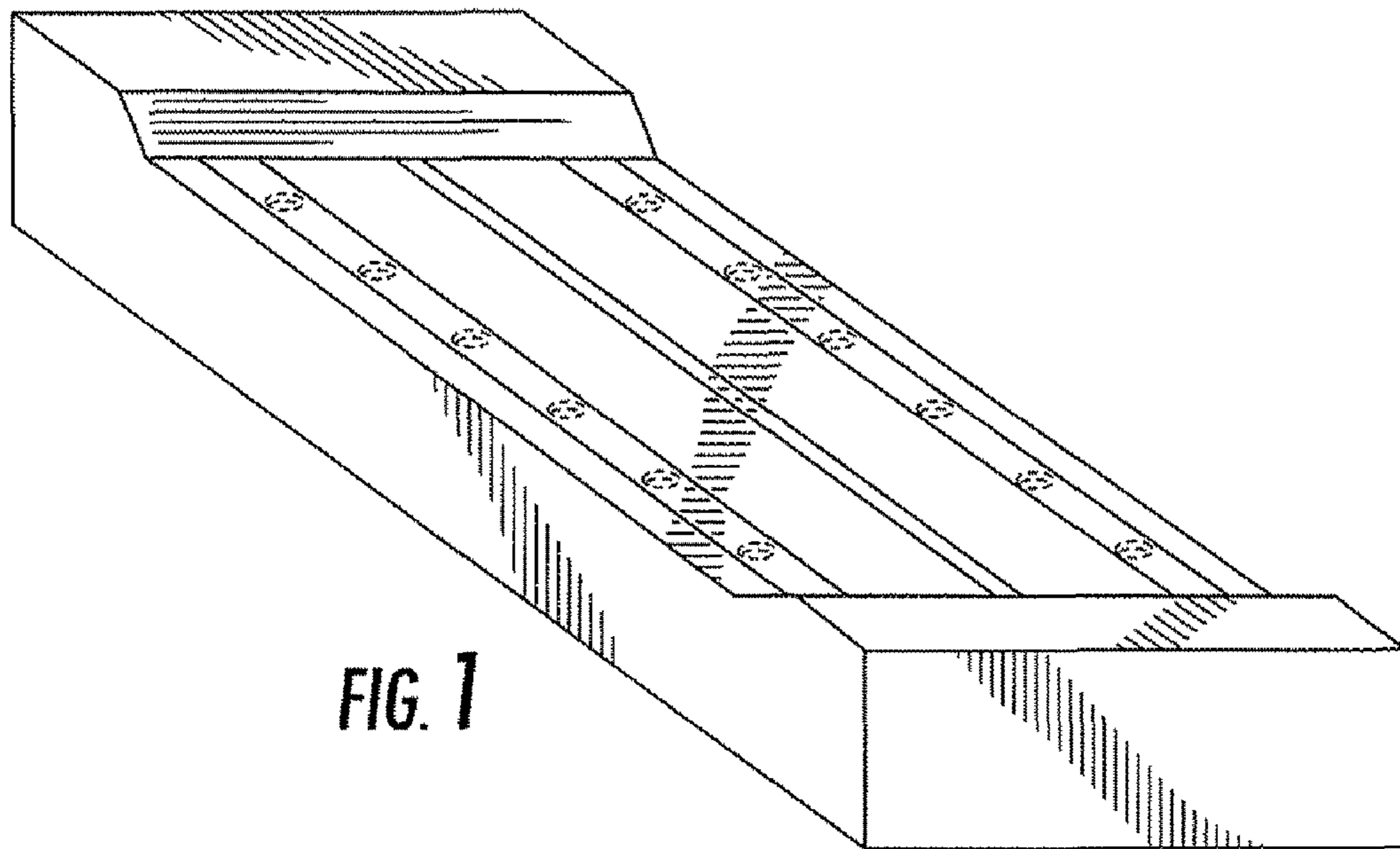
We claim the ornamental design for a molded fingerprint sensor structure with indicia regions, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a fingerprint sensor chip with integrally molded bezels including indicia regions; FIG. 2 is a left side elevation view of a fingerprint sensor chip with integrally molded bezels including indicia regions; FIG. 3 is a front elevation view of a fingerprint sensor chip with integrally molded bezels including indicia regions; FIG. 4 is a back elevation view of a fingerprint sensor chip with integrally molded bezels including indicia regions; FIG. 5 is a bottom view of a fingerprint sensor chip with integrally molded bezels including indicia regions; FIG. 6 is a top view of a fingerprint sensor chip with integrally molded bezels including indicia regions; and, FIG. 7 is a right side elevation view of a fingerprint sensor chip with integrally molded bezels including indicia regions. The broken lines depict unclaimed environmental subject matter.

1 Claim, 3 Drawing Sheets





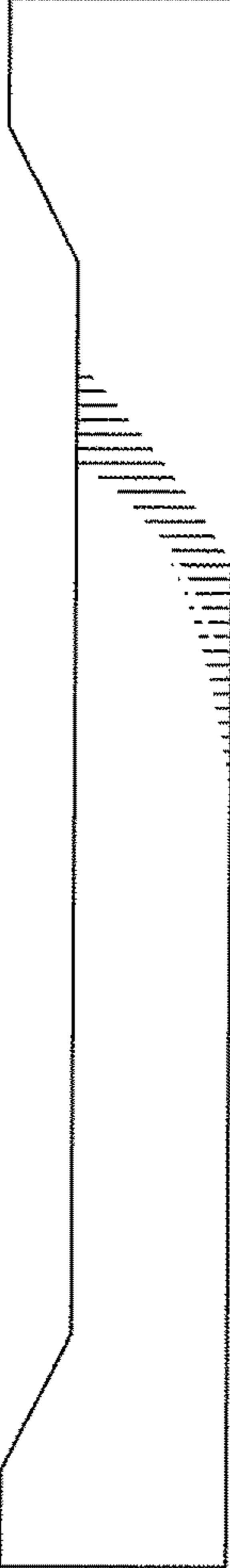


FIG. 3

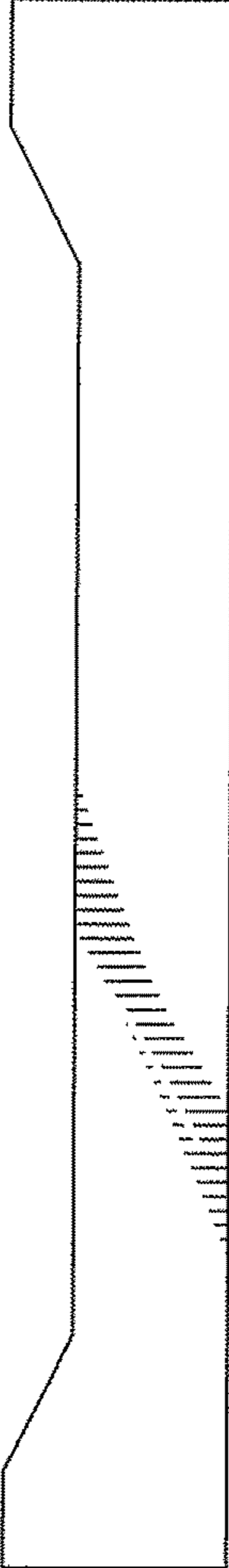


FIG. 4

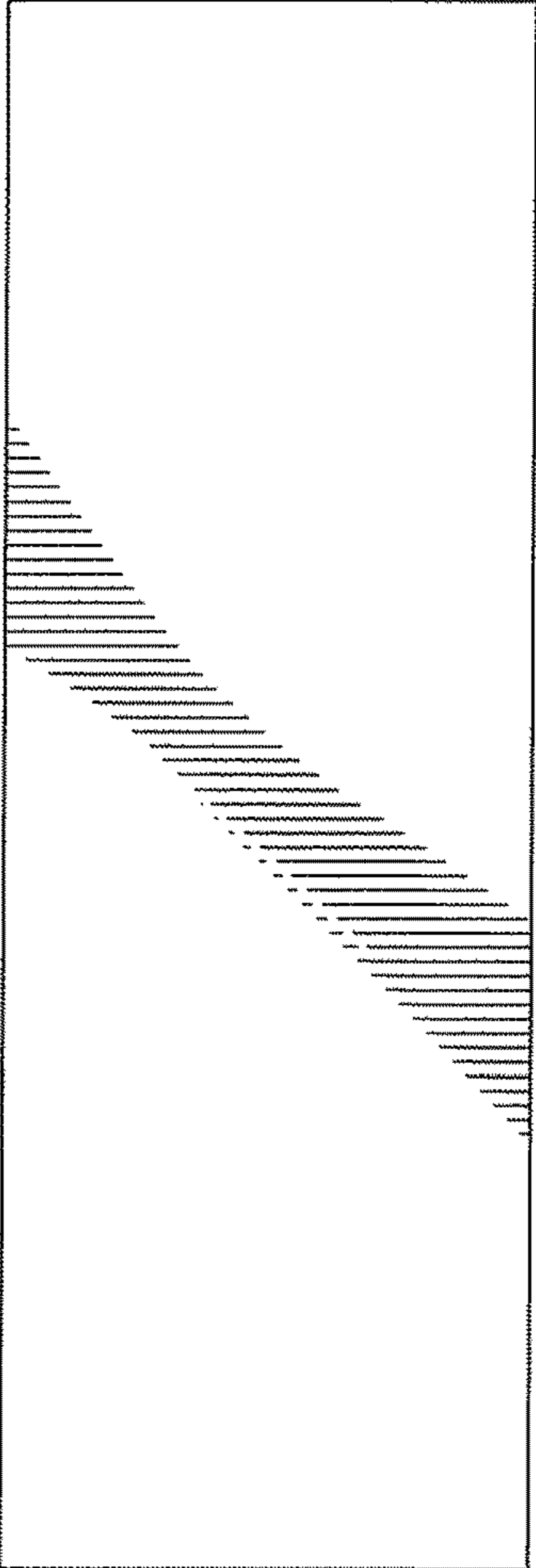


FIG. 5

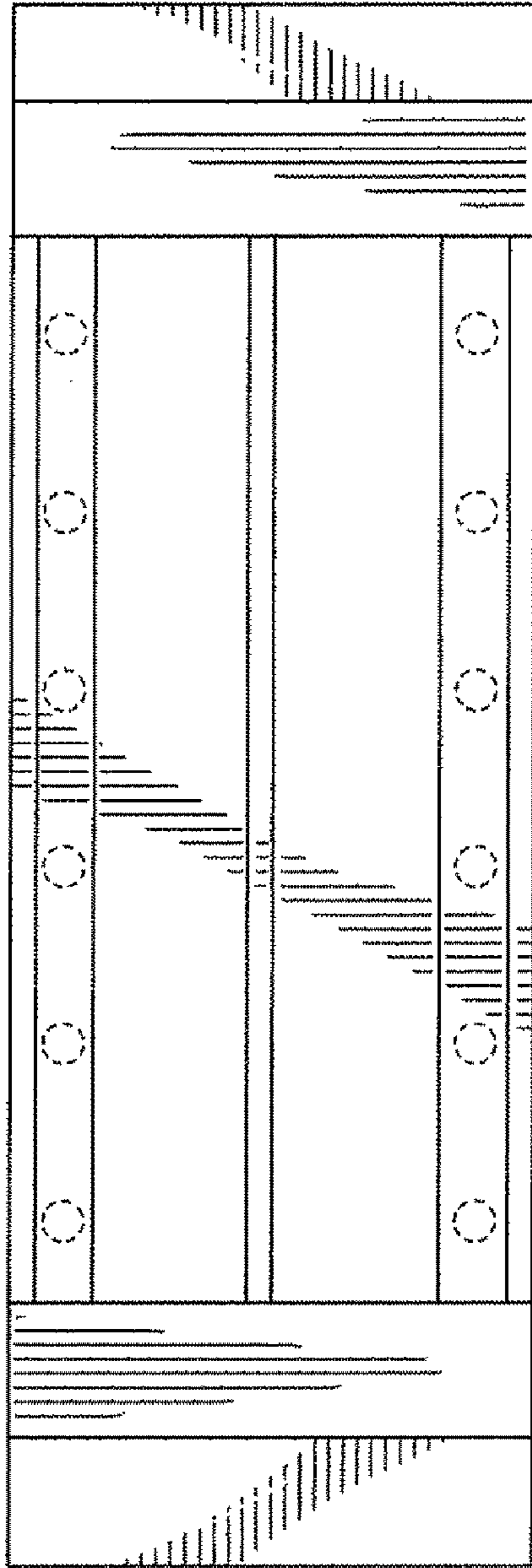


FIG. 6

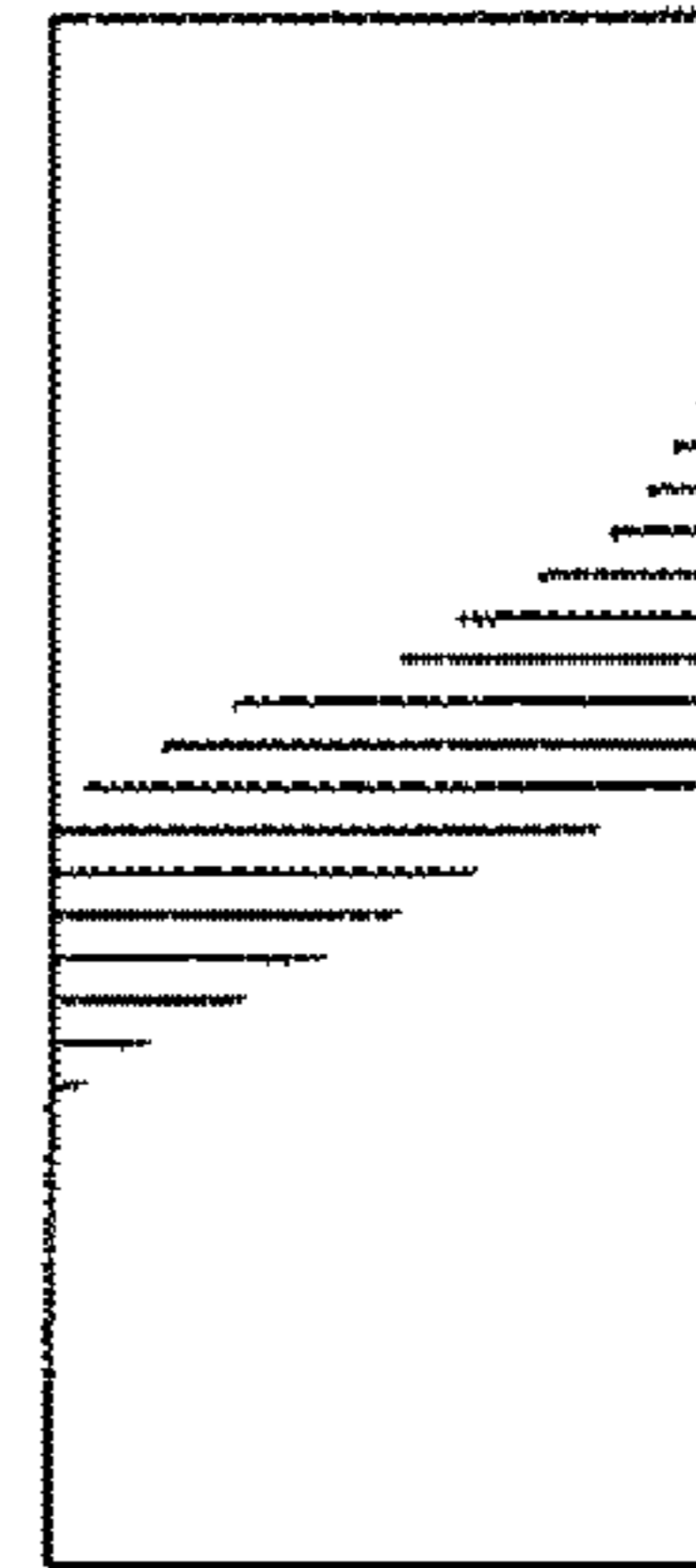


FIG. 7